

IN THE UNITED STATES  
PATENT AND TRADEMARK OFFICE

**PATENT APPLICATION**

|             |   |                 |                            |
|-------------|---|-----------------|----------------------------|
| Applicant:  | <b>Chae, et al.</b>   | Case:           | <b>APPM/8501/ETCH/DRIE</b> |
| Serial No.: | <b>10/706,902</b>   | Filed:          | <b>November 11, 2003</b>   |
| Examiner:   | <b>Tran, Binh X.</b>  | Group Art Unit: | <b>1765</b>                |
| Conf. No.:  | <b>7748</b>   |                 |                            |
| Title:      | <b>SELECTIVE ETCH PROCESS OF A SACRIFICIAL LIGHT ABSORBING MATERIAL (SLAM) OVER A DIELECTRIC MATERIAL</b> |                 |                            |

Mail Stop: AMENDMENT  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**RESPONSE TO OFFICE ACTION DATED FEBRUARY 2, 2006**

S I R:

In response to the Office Action dated February 2, 2006, having a shortened statutory period for response expired on May 2, 2006, please enter this Response and reconsider the claims pending in the application for reasons discussed below. The Applicants believe that a \$250 excess claim fee is due in connection with this response. The Commissioner is hereby authorized to charge counsel's Deposit Account No. 50-3562 for this fee, and for any other fees, including extension of time fees or additional excess claims fees, required to make this response timely and acceptable to the Office.